PRODUCT/PROCESS CHANGE NOTIFICATION #16617
Generic Copy

Issue Date: 25-March-2011

**TITLE:** Discontinuance of ASEK SnPb Plating Line and Utilize External Plating House in Taiwan

**PROPOSED FIRST SHIP DATE:** 25 June 2011 (See Note Below)

**AFFECTED CHANGE CATEGORY(S):** Assembly Site Transfer – Plating Process Only

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**
Contact your local ON Semiconductor Sales Office

**SAMPLES:** Contact your local ON Semiconductor Sales Office

**ADDITIONAL RELIABILITY DATA:** Available
Contact your local ON Semiconductor Sales Office

**NOTIFICATION TYPE:**
Termination Finish Site Change

Notification is issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

**DESCRIPTION AND PURPOSE:**

ASE Kaohsiung will phase out their internal SnPb plating process for ASE GP (Green Product) policy and will utilize their qualified external Plating house for products with SnPb plating requirement. The external plating house is Advanplating Technology Co. Ltd located in Taiwan.

**Note:** This change will actually occur earlier than the proposed first ship date identified in this PCN due to supplier’s manufacturing circumstances.
QUALIFICATION DATA:

Summary of Results

Based on the quality index for plating thickness, plating composition, appearance of product, and solder-ability, all data showed positive results; that is, Advanplating Sn-Pb plating quality can reach good plating quality performance.

AdvanPlating Technology quality performance of SnPb is no different from ASE Kaoshiung SnPb plating.

### Quality Characteristics Summary

<table>
<thead>
<tr>
<th>Quality Characteristic</th>
<th>Ideal Target</th>
<th>ASEK Mean</th>
<th>ASEK Std Dev</th>
<th>AP Mean</th>
<th>AP Std Dev</th>
<th>Result</th>
</tr>
</thead>
<tbody>
<tr>
<td>Plating thickness</td>
<td>300 - 800 μ-inch</td>
<td>503.1</td>
<td>31.7</td>
<td>496.6</td>
<td>32.1</td>
<td>SE</td>
</tr>
<tr>
<td>Plating Composition</td>
<td>80 - 90% Sn</td>
<td>84.3</td>
<td>0.42</td>
<td>87.6</td>
<td>0.34</td>
<td>SE</td>
</tr>
<tr>
<td>Solder-ability test</td>
<td>Solder coverage &gt; 95%</td>
<td>0 ppm (&lt; 95%)</td>
<td>N/A</td>
<td>0 ppm (&lt; 95%)</td>
<td>N/A</td>
<td>SE</td>
</tr>
<tr>
<td>Appearance of product</td>
<td>Follow ASE SPEC. 62-31-5130-0004 item 6.8</td>
<td>0 ppm</td>
<td>N/A</td>
<td>0 ppm</td>
<td>N/A</td>
<td>SE</td>
</tr>
</tbody>
</table>

**Legend:**
SE – Statistically Equivalent

**CHANGED PART IDENTIFICATION:**

No change in ONSEMI Part number
List of affected General Parts:

<table>
<thead>
<tr>
<th>PART</th>
</tr>
</thead>
<tbody>
<tr>
<td>11564-507-XTD</td>
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<tr>
<td>11564-507-XTP</td>
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